

Challenges for VLSI implementation of 100G digital coherent receivers

Hiroshi ONAKA

**FUJITSU Limited
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Acknowledgments

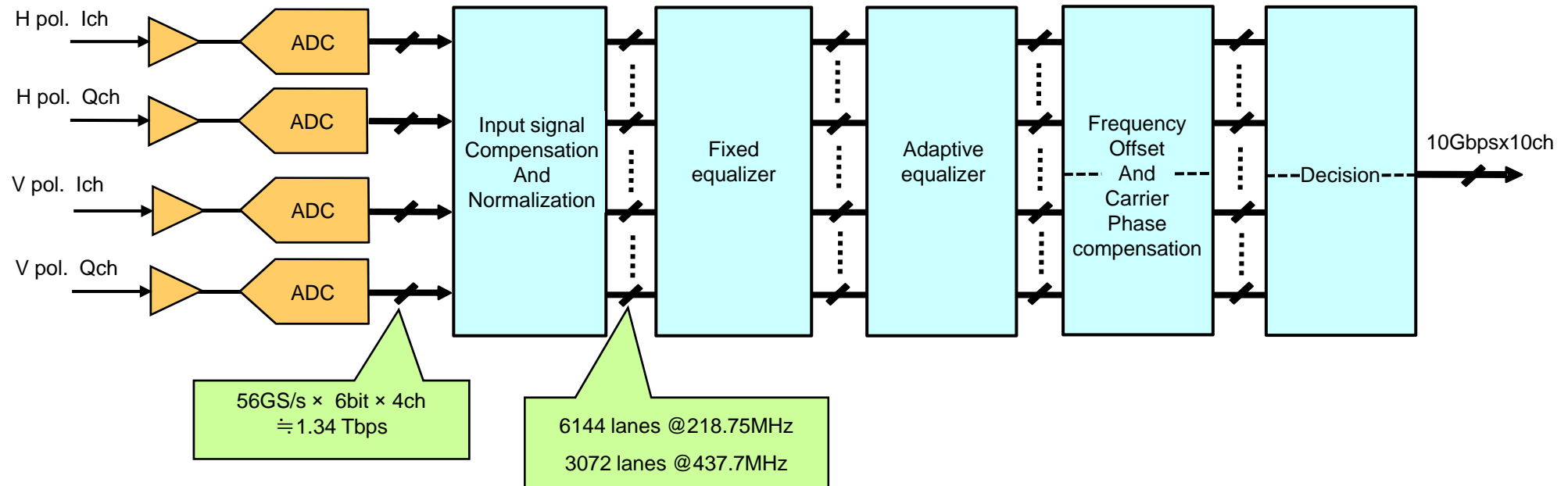


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Very much appreciate for cooperation by

- Fujitsu advanced technology
- Fujitsu Laboratories

Example configuration of 100G digital coherent LSI

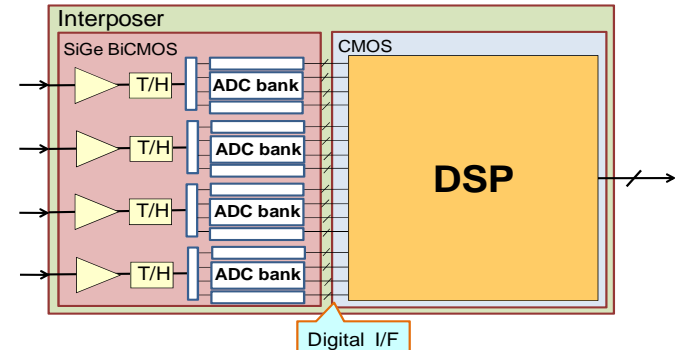
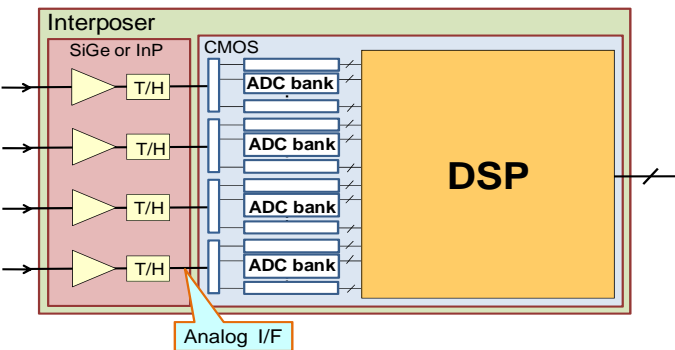
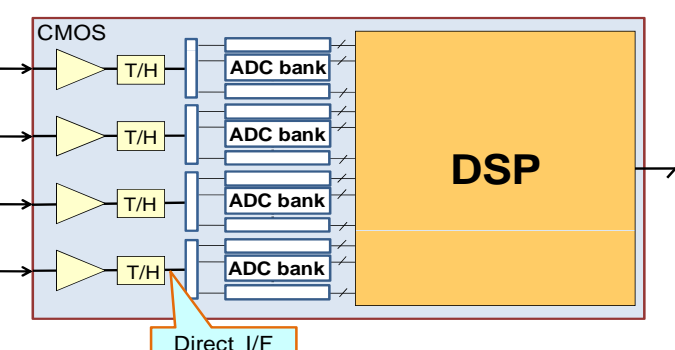


Technical challenges

- Connection between ADC and DSP
- Lower power consumption
- Efficiency improvement of LSI development

Technical challenge 1

Connection between ADC and DSP

| Case | Connection method | Technical Subjects |
|------|---|---|
| (a) |  <ul style="list-style-type: none"> • Multichip configuration <ul style="list-style-type: none"> - ADC: SiGe Bi-CMOS - DSP: CMOS • Connection with digital signal | <ul style="list-style-type: none"> • Tbps class digital interconnection between ADC and DSP • Hybrid packaging of ADC and DSP |
| (b) |  <ul style="list-style-type: none"> • Multichip configuration <ul style="list-style-type: none"> - T/H: SiGe, InP etc. - ADC Bank, DSP: CMOS • Connection with analog signal | <ul style="list-style-type: none"> • Noise and crosstalk in connection of analogue signal • Hybrid packaging of ADC and DSP |
| (c) |  <ul style="list-style-type: none"> • Monolithic configuration <ul style="list-style-type: none"> - All functions are integrated on Si • Direct connection on Si | <ul style="list-style-type: none"> • Ideal configuration • Feasibility of CMOS ADC • Mixed signal system LSI design |

Discussion about power consumption of 100G MSA module in OIF

Power Dissipation



Assumption:

- ▶ Air temperature before module: 55° C
- ▶ Module temperature: ~70° C

Maximum power dissipation:

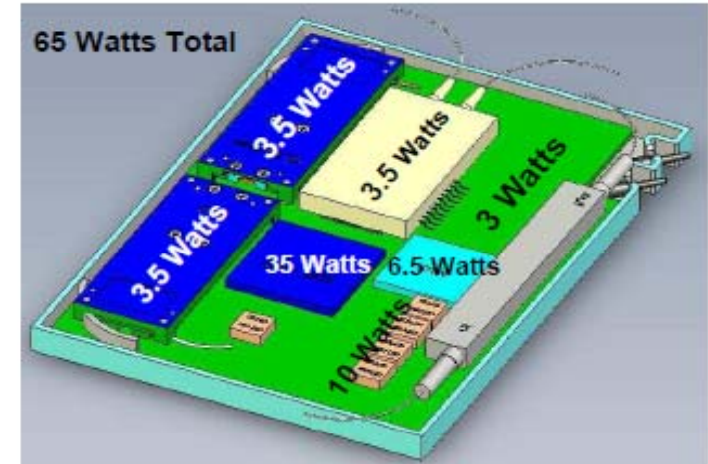
| Airflow | 20 mm height with 13 mm fins | 16 mm height with 17 mm fins |
|---------|---------------------------------|---------------------------------|
| 1 m/s | 59W | 65W |
| 2 m/s | 73W | 80W |

Question 31 - Maximum power allowed

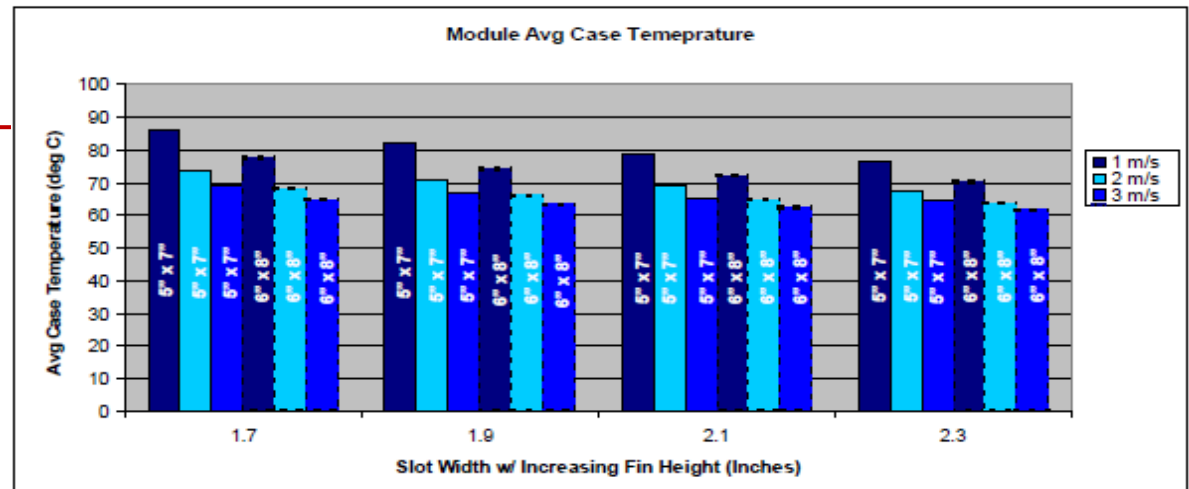
- ▶ ≤ 80W

OIF2009.052.00
Drink Barthel
CoreOptics

module size: 5 inch x 7 inch
6 inch x 8 inch



OIF2009.139.01
Roberto Marcoccia
Opnext



Technical challenge 2

Heating issue



40G DWDM 300pin MSA module

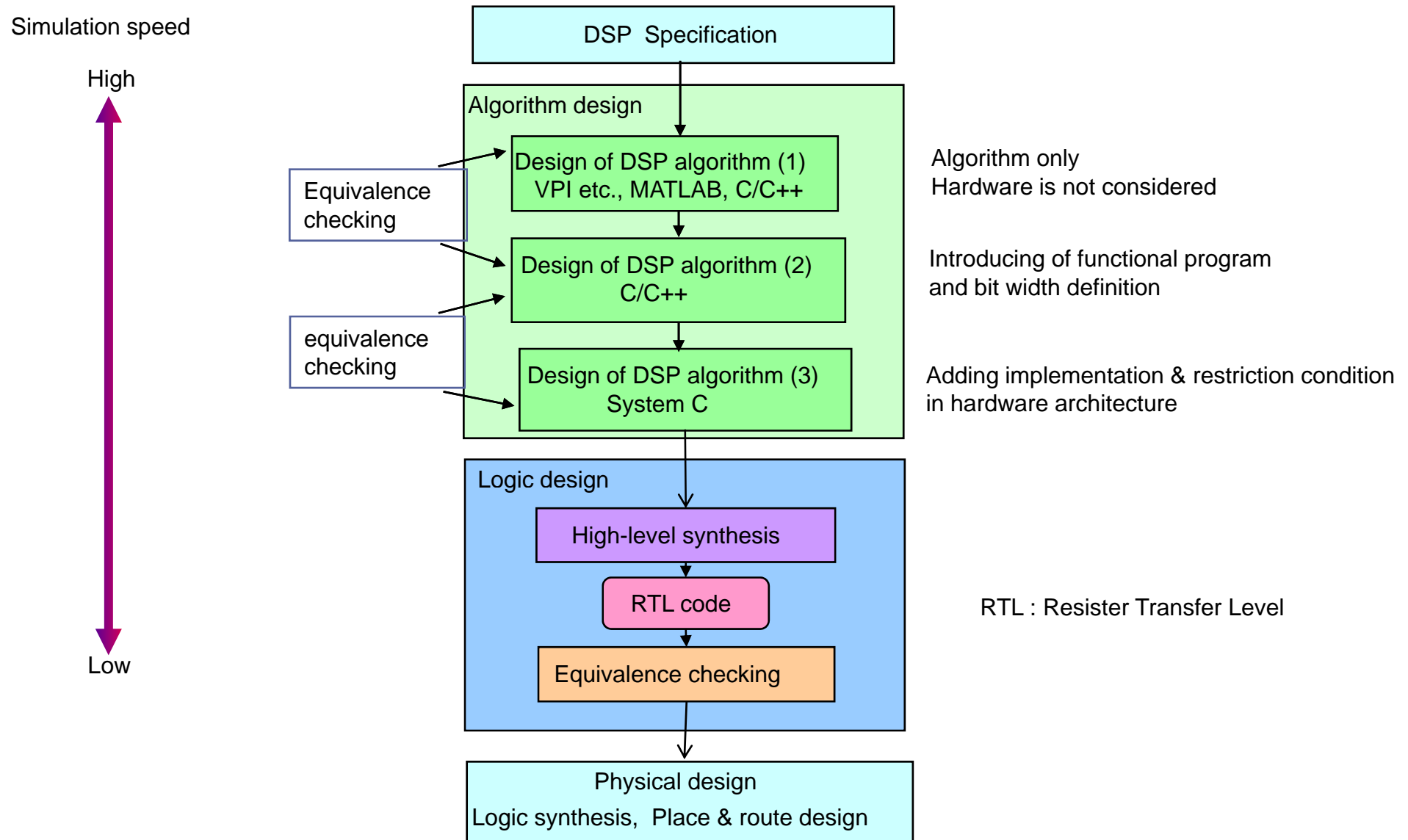
- Size: 5 inch x 7 inch
- Maximum power: ~ 30W

For 100G MSA module ?

- **65W cannot be allowed considering junction temperature of transistor**
- **For 100G MSA module, it is necessary to decrease 35W or less, and target power of LSI should be about 15W**
- **Details will be discussed in next OIF meeting**

Technical challenge 3

Efficiency improvement of VLSI development



Advantages of High-level Synthesis

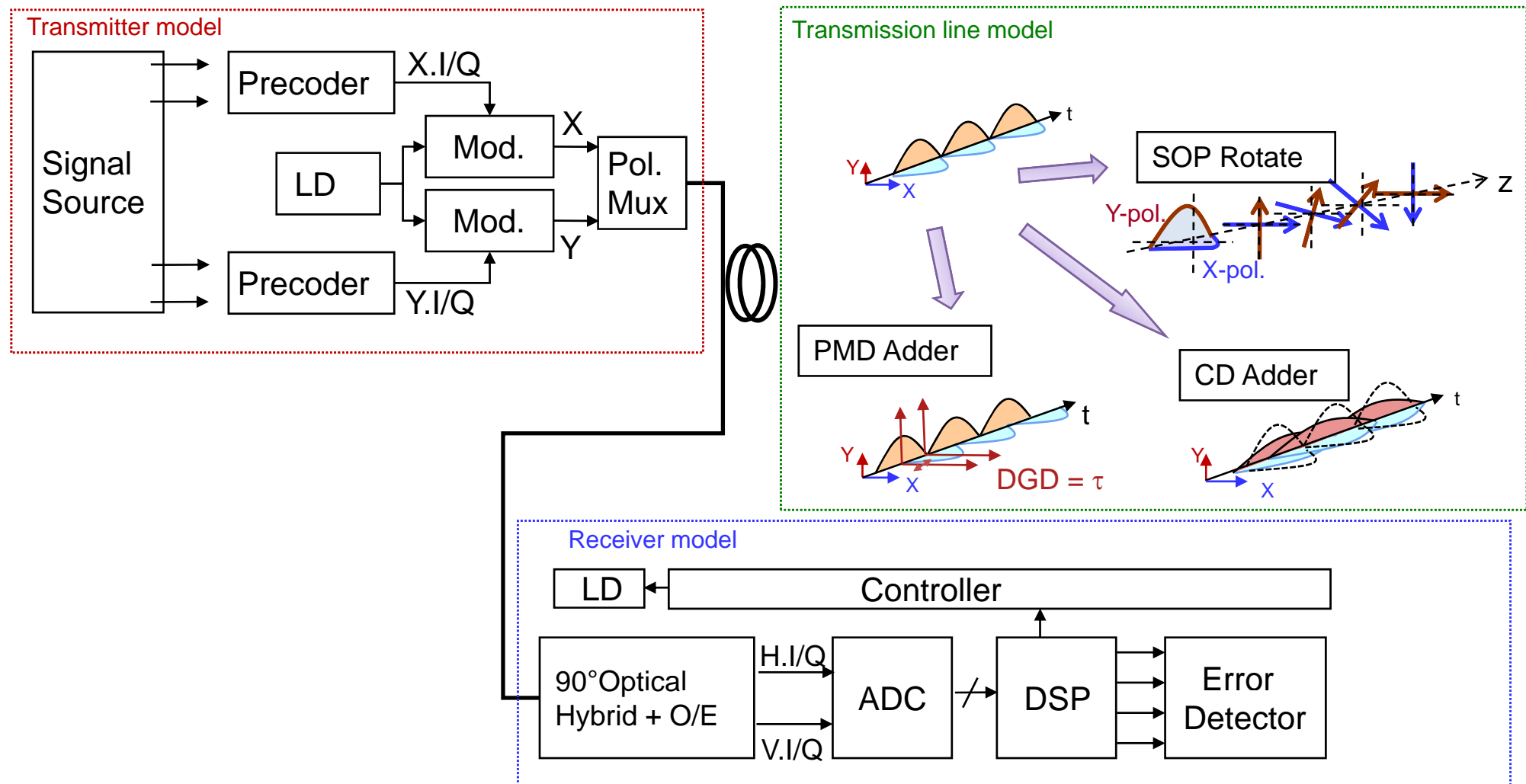


Automated design process that interprets an algorithmic description using C++/System C and creates RTL (Resister Transfer Level) code

- **Shortened design term:** Introducing automatic design at early stage
- **Decrease in design mistake:** Human error is prevented by automated synthesis
- **Expansion of design area:** Better architecture can be decided in consideration of trade-offs because various choices can design/evaluate in a short time
- **Easiness of design:** Decrease of description amount and increase of understanding level by enhancing abstraction level of design

All systems simulator including transmitter, transmission line, and receiver model

- Precise verification of DSP operation with restriction and condition of hardware by using all systems simulation

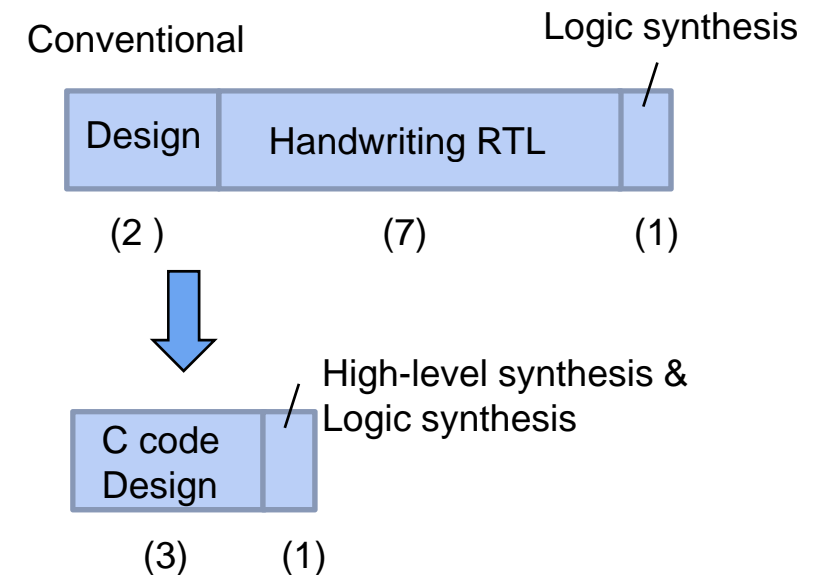


Design example by using High-level synthesis



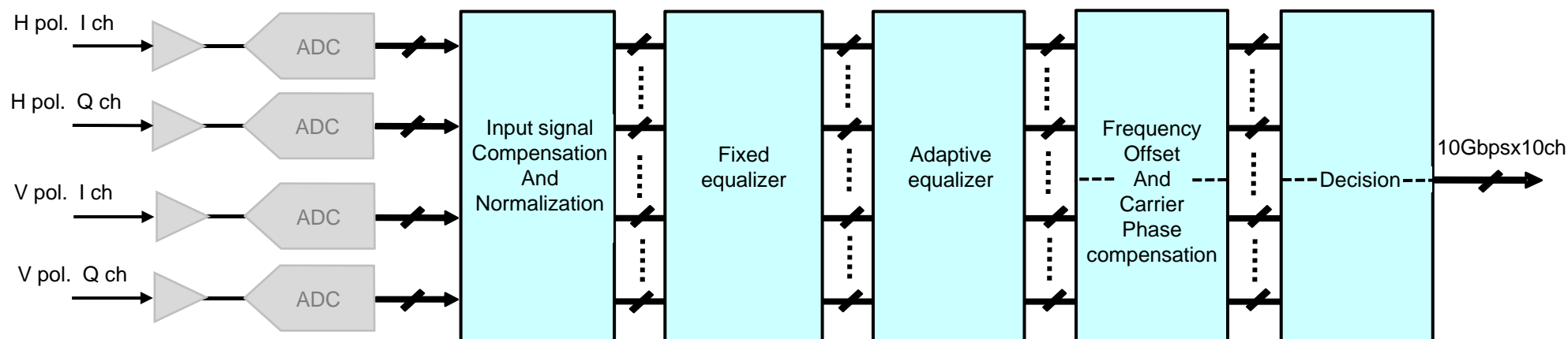
| Fixed Equalizer | Line number | Gate count |
|----------------------|-------------|---------------|
| C model (System C) | 3,091 | |
| RTL (High-synthesis) | 259,016 | 6.8M gates x2 |

| Adaptive Equalizer | Line number | Gate count |
|---------------------|-------------|------------|
| C model (System C) | 328 | |
| RTL(High-synthesis) | 42,712 | 3.4M gates |



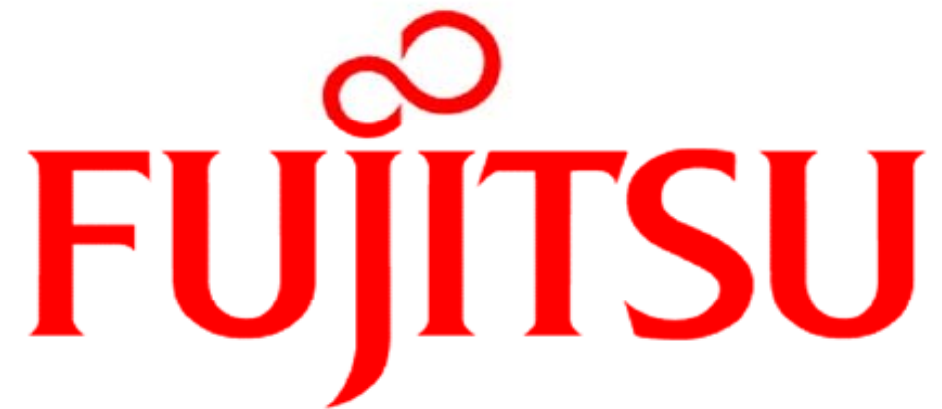
- Line number of Synthesized RTL increased to 100 times that of C model
- Line number of handwriting RTL increase to about 10 times that of C model
- Gate number by high-level synthesis confirms becoming the same as handwriting RTL

Estimated gate counts of 100G DSP



Total: 26.2 M Gates

- **100G DSP can be realized on a realistic gate scale. Necessary to reduce power by half for 5 inch x 7 inch MSA module**
- **High-level synthesis tool is very effective for development of 100G DSP**
- **All system simulation is very useful for precise verification of ADC/DSP operation**



THE POSSIBILITIES ARE INFINITE